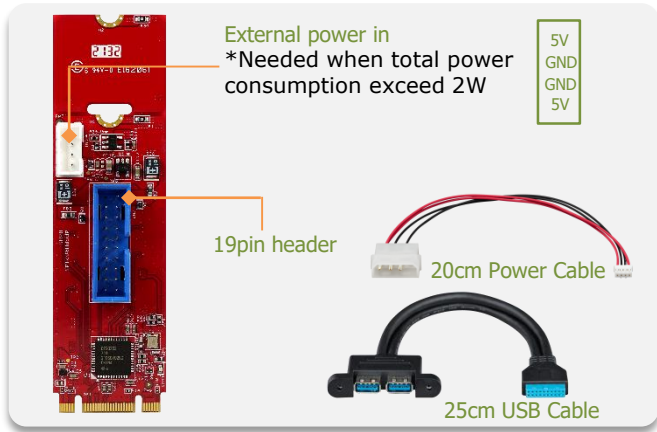


EGPU-3201

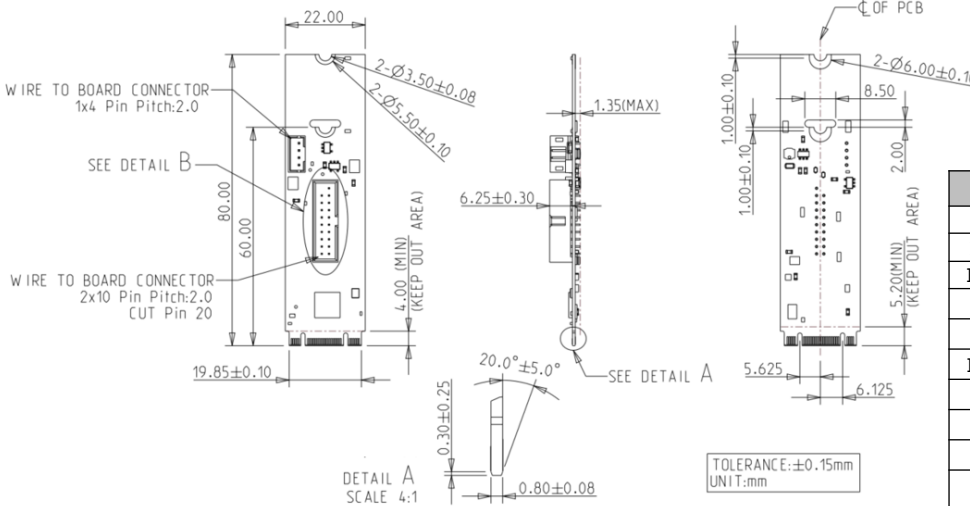
M.2 to dual USB 3.0 Module



Features

- Alternative M.2 2260 or 2280 B-M key
- Compliant with PCI Express Base Specification Revision 2.0
- Compliant with USB 3.0 Specification Revision 1.0, up to 5 Gbs
- Compliant with xHCI 1.0
- Supports 2 USB 3.0 ports (Share PCIe Gen2 x1 bandwidth)
- Supports each USB port output power up to 5V 900ma with external power in (200mA per port without external power)
- Complies with EN61000-4-2 (ESD) Air-15kV, Contact-8kV
- Optional Industrial Temperature (-40°C to +85°C) support

Mechanical Drawing



Specifications

Form-Factor	M.2 2260/2280 B+M Key
Input I/F	PCI Express 2.0
Output I/F	USB 3.0
Output Connector	19 Pin header
Power Consumption	MAX 1W (3.3V x 303mA)
Dimension (WxLxH)	22.0 x 60.0 x 8.4 mm 22.0 x 80.0 x 8.4 mm
Temperature	Operation: STD: 0°C ~ +70°C. WT: -40°C ~ +85°C Storage: -55°C ~ +95°C
Environment	Vibration: 5G @7~2000Hz, Shock: 50G @ 0.5ms
Notes	Please download driver from MyInnodisk website. Windows: XP(32 bit), 7(32/64 bit), Vista Linux: Kernel v2.6.0, v2.6.8 *After Win8 and Linux Kernel v2.6.31 supports built-in xHCI 1.0.

Headquarters (Taiwan)
5F., No.237, Sec. 1, Datong Rd.,
Xizhi Dist., New Taipei City 221,
Taiwan
Tel: +886-2-7703-3000
Email: sales@innodisk.com

Branch Offices:

USA
usasales@innodisk.com
+1-510-770-9421

Europe
eusales@innodisk.com
+31-40-3045-400

Japan
jpsales@innodisk.com
+81-3-6667-0161

China
sales_cn@innodisk.com
+86-755-2167-3689

www.innodisk.com

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November 24, 2022

Order Information

EGPU-3201-C1
M.2 2260 to dual USB 3.0 Module
EGPU-3201-C2
M.2 2280 to dual USB 3.0 Module

EGPU-3201-W1
M.2 2260 to dual USB 3.0 Module W/T
EGPU-3201-W2
M.2 2280 to dual USB 3.0 Module W/T
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